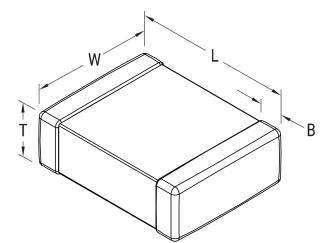


CKC21C123FDGAC7210

KC-LINK Comm COG, Ceramic, 0.012 uF, 1%, 1000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2220



Click here for the 3D model.

Dimensions		
Chip Size	2220	
L	5.9mm +/-0.4mm	
W	5mm +/-0.4mm	
Т	2.5mm +/-0.20mm	
В	0.6mm +/-0.35mm	

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	2000
Packaging Quantity	2000

General Information			
Series	KC-LINK Comm COG		
Style	SMD Chip		
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I		
Features	Ultra-Stable, Low Loss, Class I		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Component Weight	320 mg		
Shelf Life	78 Weeks		
MSL	1		

Specifications				
Capacitance	0.012 uF			
Measurement Condition	1 kHz 1.0Vrms			
Capacitance Tolerance	1%			
Voltage DC	1000 VDC			
Dielectric Withstanding Voltage	1200 VDC			
Temperature Range	-55/+150°C			
Temperature Coefficient	COG			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms			
Dissipation Factor	0.1% 1 kHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour			
Insulation Resistance	83.3333 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.